

2M × 32-Bit Dynamic RAM Module (4M × 16-Bit Dynamic RAM Module)

HYM 322000S/GS-50/-60

Advanced Information

- 2 097 152 words by 32-bit organization
(alternative 4 194 304 words by 16-bit)
- Fast access and cycle time
50 ns access time
90 ns cycle time (-50 version)
60 ns access time
110 ns cycle time (-60 version)
- Fast page mode capability with
35 ns cycle time (-50 version)
40 ns cycle time (-60 version)
- Single + 5 V (± 10 %) supply
- Low power dissipation
max. 2200 mW active (-50 version)
max. 1980 mW active (-60 version)
CMOS – 22 mW standby
TTL – 44 mW standby
- $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh, $\overline{\text{RAS}}$ -only-refresh, Hidden refresh
- 4 decoupling capacitors mounted on substrate
- All inputs, outputs and clock fully TTL compatible
- 72 pin Single in-Line Memory Module
- Utilizes four 1M × 16 -DRAMs in SOJ-42 packages
- 1024 refresh cycles / 16 ms
- Optimized for use in byte-write non-parity applications
- Tin-Lead contact pads HYM 322000S
- Gold-Lead contact pads HYM 322000GS
- single sided module with 20.32 mm (800 mil) height

The HYM 322000S/GS-50/-60 is a 8 MByte DRAM module organized as 2 097 152 words by 32-bit in a 72-pin single-in-line package comprising four HYB 5118160BSJ 1M × 16 DRAMs in 400 mil wide SOJ-packages mounted together with four 0.2 µF ceramic decoupling capacitors on a PC board.

The HYM 322000S/GS-60 can also be used as a 4 194 304 words by 16-bits dynamic RAM module by means of connecting DQ0 and DQ16, DQ1 and DQ17, DQ2 and DQ18, ..., DQ15 and DQ31, respectively.

Each HYB 5118160BSJ is described in the data sheet and is fully electrically tested and processed according to Siemens standard quality procedure prior to module assembly. After assembly onto the board, a further set of electrical tests is performed.

The speed of the module can be detected by the use of four presence detect pins.

The common I/O feature on the HYM 322000S/GS-50/-60/-70 dictates the use of early write cycles.

Ordering Information

Type	Ordering Code	Package	Descriptions
HYM 322000S-50	Q67100 - Q2052	L-SIM-72-10	DRAM module (access time 50 ns)
HYM 322000S-60	Q67100 - Q2057	L-SIM-72-10	DRAM module (access time 60 ns)
HYM 322000GS-50	Q67100 - Q2054	L-SIM-72-10	DRAM module (access time 50 ns)
HYM 322000GS-60	Q67100 - Q2059	L-SIM-72-10	DRAM module (access time 60 ns)

VSS 1 DQ0 2
DQ16 3 DQ1 4
DQ17 5 DQ2 6
DQ18 7 DQ3 8
DQ19 9 VCC 10
N.C. 11 A0 12
A1 13 A2 14
A3 15 A4 16
A5 17 A6 18
N.C. 19 DQ4 20
DQ20 21 DQ5 22
DQ21 23 DQ6 24
DQ22 25 DQ7 26
DQ23 27 A7 28
N.C. 29 VCC 30
A8 31 A9 32
RAS3 33 RAS2 34
N.C. 35 N.C. 36

N.C. 37 N.C. 38
VSS 39 CAS0 40
CAS2 41 CAS3 42
CAS1 43 RAS0 44
RAS1 45 N.C. 46
WE 47 N.C. 48
DQ8 49 DQ24 50
DQ9 51 DQ25 52
DQ10 53 DQ26 54
DQ11 55 DQ27 56
DQ12 57 DQ28 58
VCC 59 DQ29 60
DQ13 61 DQ30 62
DQ14 63 DQ31 64
DQ15 65 N.C. 66
PD0 67 PD1 68
PD2 69 PD3 70
N.C. 71 VSS 72

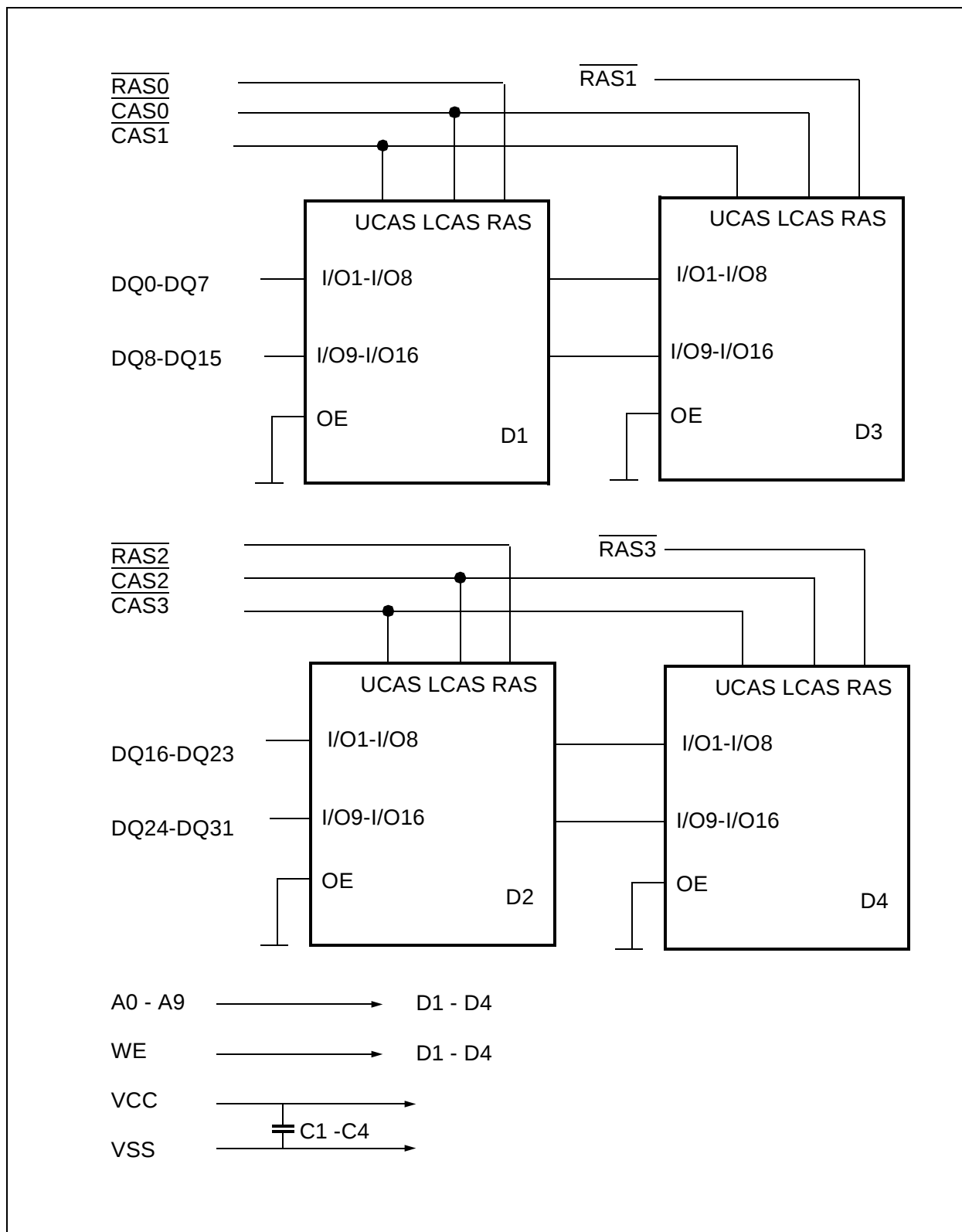
Pin Names

A0-A9	Address Inputs
DQ0-DQ31	Data Input/Output
CAS0 - CAS3	Column Address Strobe
RAS0 - RAS3	Row Address Strobe
WE	Read/Write Input
V _{CC}	Power (+ 5 V)
V _{SS}	Ground
PD	Presence Detect Pin
N.C.	No Connection

Presence Detect Pins

	-50	-60
PD0	N.C.	N.C.
PD1	N.C.	N.C.
PD2	V _{SS}	N.C.
PD3	V _{SS}	N.C.

Pin Configuration



Absolute Maximum Ratings

Operating temperature range 0 to + 70 °C
 Storage temperature range..... – 55 to + 125 °C
 Input/output voltage – 1 to + 7 V
 Power supply voltage..... – 1 to + 7 V
 Power dissipation..... 2.52 W
 Data out current (short circuit) 50 mA

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics ¹⁾

$T_A = 0$ to 70 °C; $V_{CC} = 5$ V $\pm$ 10 %

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Input high voltage	V_{IH}	2.4	5.5	V	–
Input low voltage	V_{IL}	– 1.0	0.8	V	–
Output high voltage ($I_{OUT} = -5$ mA)	V_{OH}	2.4	–	V	–
Output low voltage ($I_{OUT} = 4.2$ mA)	V_{OL}	–	0.4	V	–
Input leakage current (0 V < V_{IN} < 6.5 V, all other pins = 0 V)	$I_{I(L)}$	– 20	20	μA	–
Output leakage current (DO is disabled, 0 V < V_{OUT} < 5.5 V)	$I_{O(L)}$	– 10	10	μA	–
Average V_{CC} supply current: HYM 322000S/GS-50 HYM 322000S/GS-60 ($\overline{RAS}$, $\overline{CAS}$, address cycling, $t_{RC} = t_{RC}$ min.)	I_{CC1}	– – –	400 360	mA mA	2), 3), 4)
Standby V_{CC} supply current ($\overline{RAS} = \overline{CAS} = V_{IH}$)	I_{CC2}	–	8	mA	–
Average V_{CC} supply current during $\overline{RAS}$ only refresh cycles: HYM 322000S/GS-50 HYM 322000S/GS-60 ($\overline{RAS}$ cycling, $\overline{CAS} = V_{IH}$, $t_{RC} = t_{RC}$ min.)	I_{CC3}	– – –	400 360	mA mA	2), 4)

DC Characteristics (cont'd) ¹⁾

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Average V_{CC} supply current during fast page mode: HYM 322000S/GS-50 HYM 322000S/GS-60 ($\overline{RAS} = V_{IL}$, $\overline{CAS}$, address cycling $t_{PC} = t_{PC \text{ min.}}$)	I_{CC4}	— — —	110 100	mA mA	2), 3), 4)
Standby V_{CC} supply current ($\overline{RAS} = \overline{CAS} = V_{CC} - 0.2 \text{ V}$)	I_{CC5}	—	4	mA	—
Average V_{CC} supply current during CAS-before-RAS refresh HYM 322000S/GS-50 HYM 322000S/GS-60 ($\overline{RAS}$, $\overline{CAS}$ cycling, $t_{RC} = t_{RC \text{ min.}}$)	I_{CC6}	— — —	400 360	mA mA	29), 4)

Capacitance
 $T_A = 0 \text{ to } 70 \text{ }^\circ\text{C}$; $V_{CC} = 5 \text{ V} \pm 10 \%$; $f = 1 \text{ MHz}$

Parameter	Symbol	Limit Values		Unit
		min.	max.	
Input capacitance (A0 to A9)	C_{I1}	—	35	pF
Input capacitance ($\overline{RAS0}$, $\overline{RAS2}$)	C_{I2}	—	20	pF
Input capacitance ($\overline{CAS0}$ – $\overline{CAS3}$)	C_{I3}	—	20	pF
Input capacitance ($\overline{WE}$)	C_{I4}	—	35	pF
I/O capacitance (DQ0-DQ31)	C_{IO1}	—	25	pF

AC Characteristics ⁵⁾⁶⁾

M16F

 $T_A = 0 \text{ to } 70 \text{ }^\circ\text{C}, V_{CC} = 5 \text{ V} \pm 10 \%, t_T = 5 \text{ ns}$

Parameter	Symbol	Limit Values				Unit	Note
		-50		-60			
		min.	max.	min.	max.		

common parameters

Random read or write cycle time	t_{RC}	90	—	110	—	ns	
$\overline{\text{RAS}}$ precharge time	t_{RP}	30	—	40	—	ns	
$\overline{\text{RAS}}$ pulse width	t_{RAS}	50	10k	60	10k	ns	
$\overline{\text{CAS}}$ pulse width	t_{CAS}	13	10k	15	10k	ns	
Row address setup time	t_{ASR}	0	—	0	—	ns	
Row address hold time	t_{RAH}	8	—	10	—	ns	
Column address setup time	t_{ASC}	0	—	0	—	ns	
Column address hold time	t_{CAH}	10	—	15	—	ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ delay time	t_{RCD}	18	37	20	45		
$\overline{\text{RAS}}$ to column address delay time	t_{RAD}	13	25	15	30	ns	
$\overline{\text{RAS}}$ hold time	t_{RSH}	13		15	—	ns	
$\overline{\text{CAS}}$ hold time	t_{CSH}	50		60	—	ns	
$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ precharge time	t_{CRP}	5	—	5	—	ns	
Transition time (rise and fall)	t_T	3	50	3	50	ns	7
Refresh period	t_{REF}	—	16	—	16	ms	

Read Cycle

Access time from $\overline{\text{RAS}}$	t_{RAC}	—	50	—	60	ns	8, 9
Access time from $\overline{\text{CAS}}$	t_{CAC}	—	13	—	15	ns	8, 9
Access time from column address	t_{AA}	—	25	—	30	ns	8,10
Column address to $\overline{\text{RAS}}$ lead time	t_{RAL}	25	—	30	—	ns	
Read command setup time	t_{RCS}	0	—	0	—	ns	
Read command hold time	t_{RCH}	0	—	0	—	ns	11
Read command hold time referenced to $\overline{\text{RAS}}$	t_{RRH}	0	—	0	—	ns	11
$\overline{\text{CAS}}$ to output in low-Z	t_{CLZ}	0	—	0	—	ns	8
Output buffer turn-off delay	t_{OFF}	0	13	0	15	ns	12

AC Characteristics (cont'd) ⁵⁾⁶⁾

M16F

$T_A = 0 \text{ to } 70 \text{ }^\circ\text{C}$, $V_{CC} = 5 \text{ V} \pm 10 \%$, $t_T = 5 \text{ ns}$

Parameter	Symbol	Limit Values				Unit	Note
		-50		-60			
		min.	max.	min.	max.		

Early Write Cycle

Write command hold time	t_{WCH}	8	—	10	—	ns	
Write command pulse width	t_{WP}	8	—	10	—	ns	
Write command setup time	t_{WCS}	0	—	0	—	ns	13
Write command to $\overline{\text{RAS}}$ lead time	t_{RWL}	13	—	15	—	ns	
Write command to $\overline{\text{CAS}}$ lead time	t_{CWL}	13	—	15	—	ns	
Data setup time	t_{DS}	0	—	0	—	ns	14
Data hold time	t_{DH}	10	—	10	—	ns	14

Fast Page Mode Cycle

Fast page mode cycle time	t_{PC}	35	—	40	—	ns	
$\overline{\text{CAS}}$ precharge time	t_{CP}	10	—	10	—	ns	
Access time from $\overline{\text{CAS}}$ precharge	t_{CPA}	—	30	—	35	ns	7
$\overline{\text{RAS}}$ pulse width	t_{RAS}	50	200k	60	200k	ns	
$\overline{\text{CAS}}$ precharge to $\overline{\text{RAS}}$ Delay	t_{RHCP}	30	—	35	—	ns	

$\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ Refresh Cycle

$\overline{\text{CAS}}$ setup time	t_{CSR}	10	—	10	—	ns	
$\overline{\text{CAS}}$ hold time	t_{CHR}	10	—	10	—	ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ precharge time	t_{RPC}	5	—	5	—	ns	
Write to $\overline{\text{RAS}}$ precharge time	t_{WRP}	10	—	10	—	ns	
Write hold time referenced to $\overline{\text{RAS}}$	t_{WRH}	10	—	10	—	ns	

Notes:

- 1) All voltages are referenced to VSS.
- 2) ICC1, ICC3, ICC4 and ICC6 depend on cycle rate.
- 3) ICC1 and ICC4 depend on output loading. Specified values are measured with the output open.
- 4) Address can be changed once or less while $\overline{\text{RAS}} = \text{VIL}$. In the case of ICC4 it can be changed once or less during a fast page mode cycle (tPC).
- 5) An initial pause of 200 μs is required after power-up followed by 8 $\overline{\text{RAS}}$ cycles of which at least one cycle has to be a refresh cycle, before proper device operation is achieved. In case of using internal refresh counter, a minimum of 8 $\overline{\text{CAS}}$ -before-RAS initialization cycles instead of 8 $\overline{\text{RAS}}$ cycles are required.
- 6) AC measurements assume $t_T = 5 \text{ ns}$.
- 7) VIH (min.) and VIL (max.) are reference levels for measuring timing of input signals. Transition times are also measured between VIH and VIL .
- 8) Measured with a load equivalent to 2 TTL loads and 100 pF.
- 9) Operation within the tRCD (max.) limit ensures that tRAC (max.) can be met. tRCD (max.) is specified as a reference point only: If tRCD is greater than the specified tRCD (max.) limit, then access time is controlled by tCAC.
- 10) Operation within the tRAD (max.) limit ensures that tRAC (max.) can be met. tRAD (max.) is specified as a reference point only: If tRAD is greater than the specified tRAD (max.) limit, then access time is controlled by tAA.
- 11) Either tRCH or tRRH must be satisfied for a read cycle.
- 12) tOFF (max.) define the time at which the outputs achieve the open-circuit condition and are not referenced to output voltage levels.
- 13) tWCS is not a restrictive operating parameter. This is included in the data sheet as electrical characteristics only. If $t\text{WCS} > t\text{WCS}(\text{min.})$, the cycle is an early write cycle and the I/O pin will remain open-circuit (high impedance) through the entire cycle.
- 14) These parameters are referenced to the $\overline{\text{CAS}}$ leading edge.

Technical drawing of a PCB layout showing dimensions and tolerances. The drawing includes a top view and a side view.

Top View Dimensions:

- Overall width: 107.95
- Overall length: 101.19
- Left side dimensions: 3.38, 20.32, 6.35, 2.03, 6.35
- Right side dimensions: 10.16, 8.89 max.
- Bottom side dimensions: 1.27, 6.35 ± 0.05 , 95.25 ± 0.05 , 1.27
- Radius: R1.57
- Internal dimensions: 1.27, 6.35 ± 0.05

Side View Dimensions:

- Overall height: 7.2 min.
- Internal height: 10.16
- Radius: R1.57 ± 0.05
- Bottom width: 1.27 $+0.10/-0.08$

Detail of Contacts:

- Overall width: 1.27
- Overall height: 2.54 min.
- Internal height: 0.25 max.
- Internal width: 1.04 ± 0.05

Tolerances: ± 0.13 unless otherwise specified

Semiconductor Group